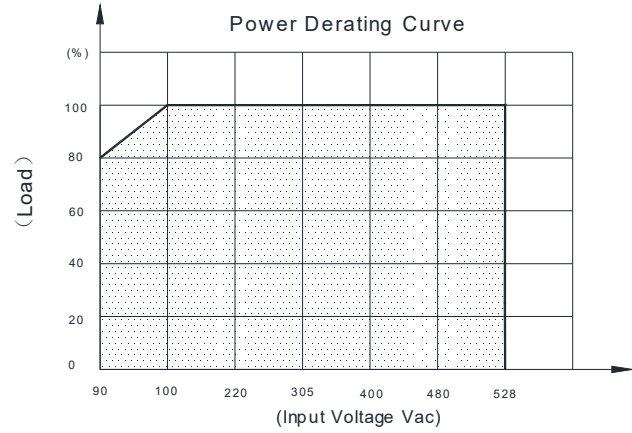
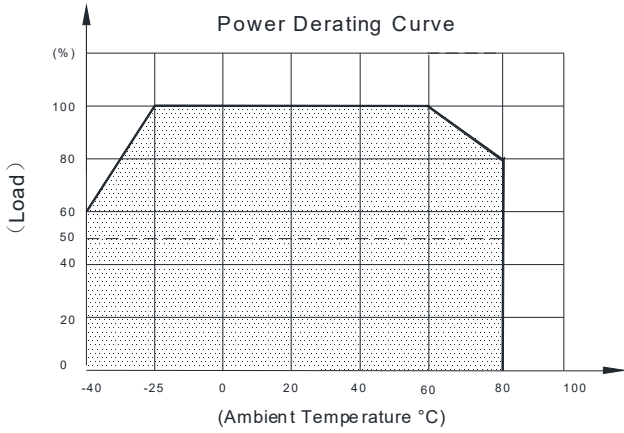




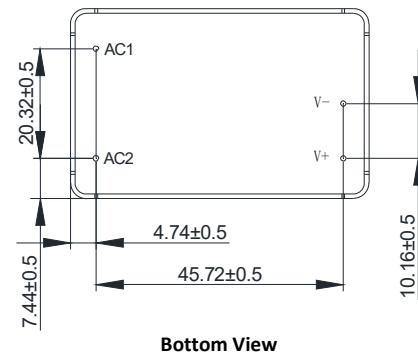
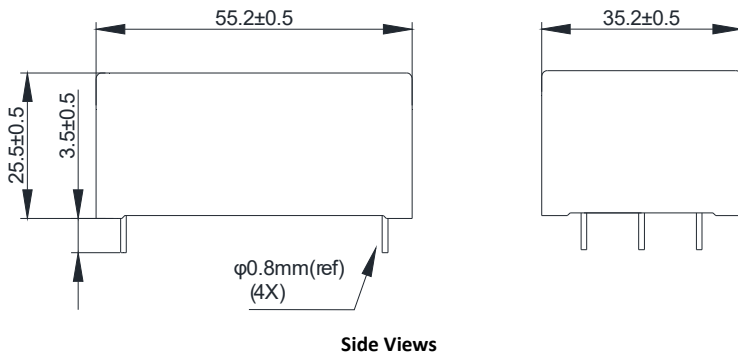
**ELECTRICAL SPECIFICATIONS**

Model No.		HPI10SXX00E	
Input	Rated Voltage	100-480VAC & 120VDC-745VDC	
	Input Voltage Range	90-528VAC	
	Frequency (Hz)	47-63 Hz	
	Current (Full load)	100VAC	480VAC
		220mA	52mA
	Inrush Current (<500us)	20A	35A
	No Load Loss	0.75W Max	
HOT PLUG	Unavailable		
Output	Voltage (V)	See model list	
	Current (mA) max.		
	Voltage Accuracy	±5%	
	Line Regulation	±5%	
	Load Regulation	±5%	
	Minimum Load (mA)	0	
	Ripple & Noise (mV)	Vout * 3% / 20MHz bandwidth (peak-to-peak value)	
	Efficiency (typ.)	See model list	
	Set-up Time	3s	
	Hold up Time	15ms min	
Protection	Over Current Protection	Hiccup mode	
	Short Circuit Protection	Hiccup mode	
Environment	Operating Temperature	-40°C...+ 80°C (see Derating Curve) @Free air convection	
	Operating Humidity	10-90% RH	
	Storage Temperature	-40°C...+85°C	
	Storage Humidity	5-95% RH	
	Temperature Coefficient	±0.04%/°C (0~60°C)	
Physical	Case Material	Plastic ( UL 94V-0)	
	Weight	74g (ref.)	
Safety & EMC	Dielectric Strength	I/P-O/P : 4KVAC	
	Safety Standards	UL 62368-1 (Class II)	
	EMI	CISPR32/EN55032 CLASS B	
	EMS (Noise Immunity)	ESD ±4KV contact; ±8KV Air EN 61000-4-2:2009 Criteria B SURGE ±2KV EN 61000-4-5 Criteria A EFT ±2KV EN 61000-4-4 Criteria A	
Reliability Requirement	MTBF	300KHrs Min @480VAC MIL-HDBK-217F (25°C)	
	Burn-In Test	The unit shall be burned in for 2~4 Hours under 480Vac input and DC with full load at 25°C	

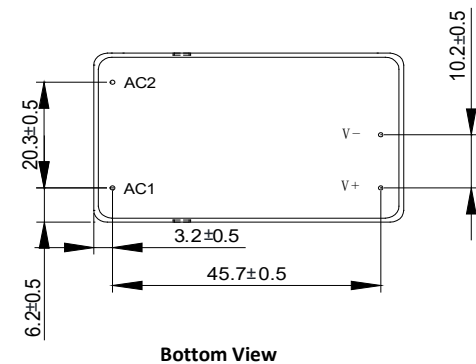
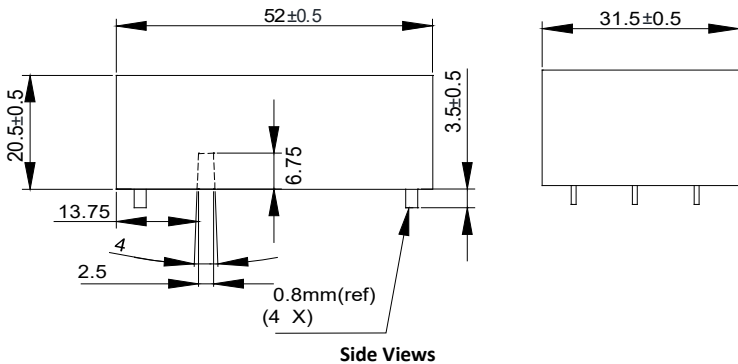
**DERATING CURVES**



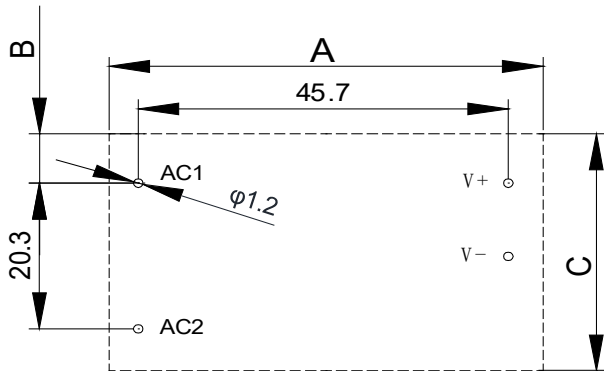
**MECHANICAL SPECIFICATIONS – DEFAULT CASE SIZE**



**MECHANICAL SPECIFICATIONS – REDUCED CASE SIZE (available for 5Vdc only)**

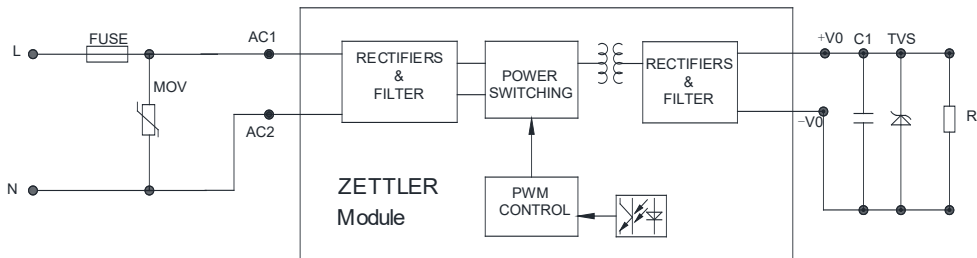


**PCB LAYOUT**



	Default (*ED)	Reduced (*ER)
A	56mm	53mm
B	7.85mm	6.55mm
C	36mm	32.3mm

**TYPICAL APPLICATION SCHEMATIC**

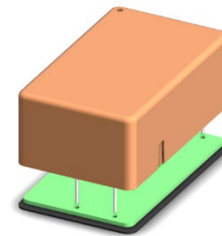


ITEM	MOV	FUSE
1~2W	14 D91 1K	1A/600V
3~5W	14 D91 1K	2A/600V
10~20W	14 D91 1K	3.15 A/600V

Note: External circuit components are only recommendations, customers should choose their own components and values according to their specific system application requirements.

**SHIELDING**

The base of HPI10 power modules integrate a shield plane allowing system designers to easily implement 6-sided shielding. An optional top shield can be added and bonded to digital ground (-V0) in order to minimize radiated noise from the power supply interfering with sensitive communications receivers.



Contact ZETTLER for bundling a shield with the HPI10 power module or to obtain 3D files. If designing your own shield, creepages and clearances around the AC input need to be considered.